

A graph showing the relationship between BSE Signal Amplitude (Y-axis) and Detector Output (X-axis). The signal amplitude is constant at a high level for low detector output, then decreases linearly to a minimum, increases linearly to a peak, decreases linearly to a minimum, increases linearly to a peak, decreases linearly to a minimum, and finally increases linearly to a high level for high detector output. This pattern is characteristic of a sawtooth wave.

1(B)

The graph shows the BSE Signal Amplitude on the vertical axis and the Detector Output on the horizontal axis. The signal amplitude is constant at a high level for low detector output, then drops to a minimum value at a specific detector output, and finally rises back to the original high level as the detector output increases further.

FIG. 1(C)

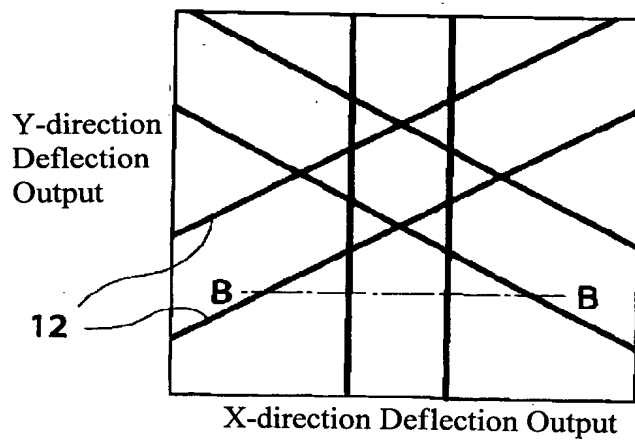


FIG. 2(A)

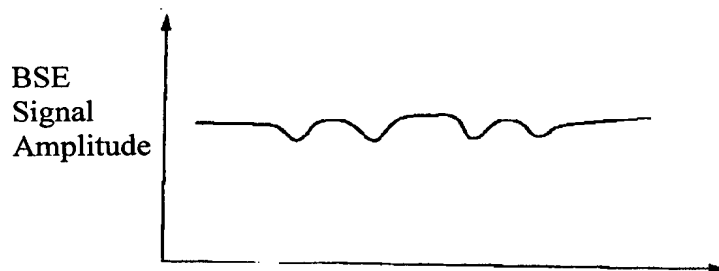


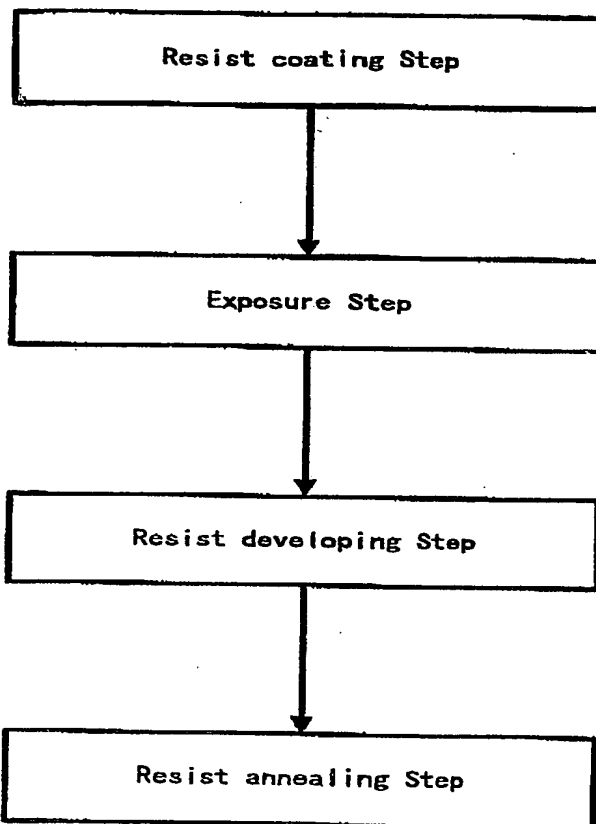
FIG. 2(B)



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graph TD; A[Wafer Production Step] --> B(WAFER); B --> C[Wafer Processing Step]; C --> D[Assembly Step]; D --> E(CHIP); E --> F[Inspection Step]; F --> G(Semiconductor Device); H[Mask Production Step] --> I(Reticle, Mask); I --> J[Lithography Step]; J <--> K[CVD<br/>Sputtering<br/>Oxidation<br/>Ion implantation<br/>Etching]; K <--> L[Cleaning Step]; J --> M(REPEAT); L --> M; M --> C;
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The flowchart illustrates the semiconductor production process, starting with two parallel paths: Wafer Production and Mask Production. The Wafer Production path leads to a WAFER, which then undergoes Wafer Processing. The Mask Production path leads to a Reticle, Mask, which is used in the Lithography Step. The Lithography Step is part of a cycle that includes CVD, Sputtering, Oxidation, Ion implantation, Etching, and a Cleaning Step. This cycle is repeated until the process moves to the Assembly Step, resulting in a CHIP. The CHIP then undergoes an Inspection Step before becoming a Semiconductor Device.

• *Staphylococcus aureus* is the most common cause of skin infections.



Lithography Step

FIG. 5